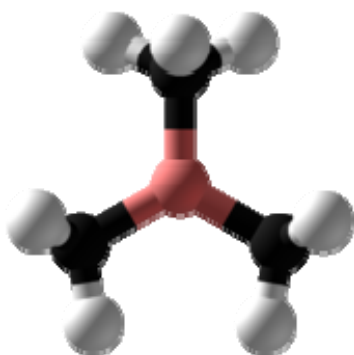


# A surface inhibiting effect in chemical vapor deposition of boron-carbon thin films from trimethylboron

Laurent Souqui, Hans Högberg, Henrik Pedersen

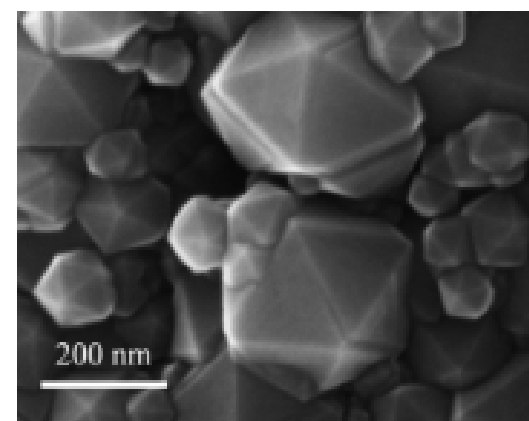
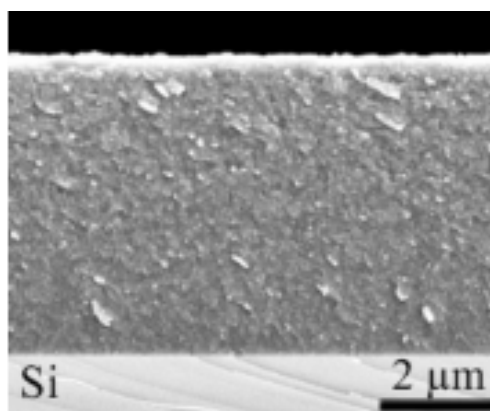
*Department of Physics, Chemistry and Biology*

## Boron-Carbon films from Trimethylboron



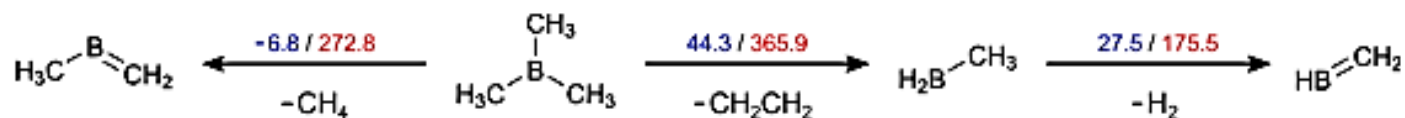
Trimethylboron  
 $\text{B}(\text{CH}_3)_3$   
TMB

- Very few studies
- Investigated gas phase chemistry:
  - Between 500 °C and 1200 °C
  - Pyrolysis starts around 650 °C
  - Amorphous and crystalline boron carbide



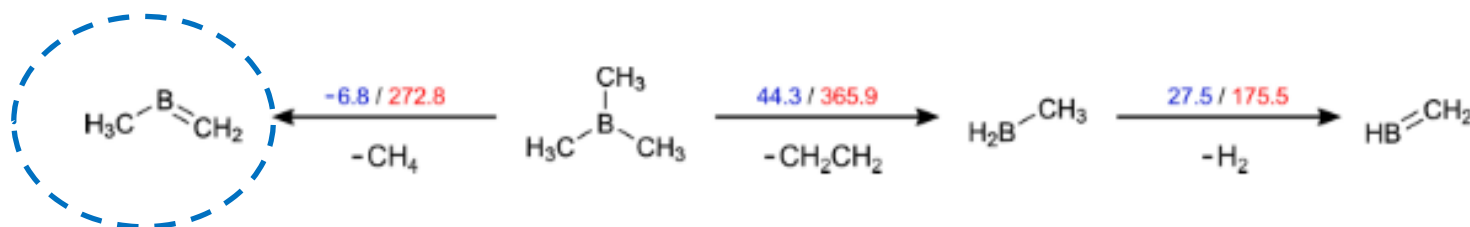
## Boron-Carbon films from Trimethylboron

From Quantum chemical calculations:  
Decomposition in Ar ambient at 800 °C



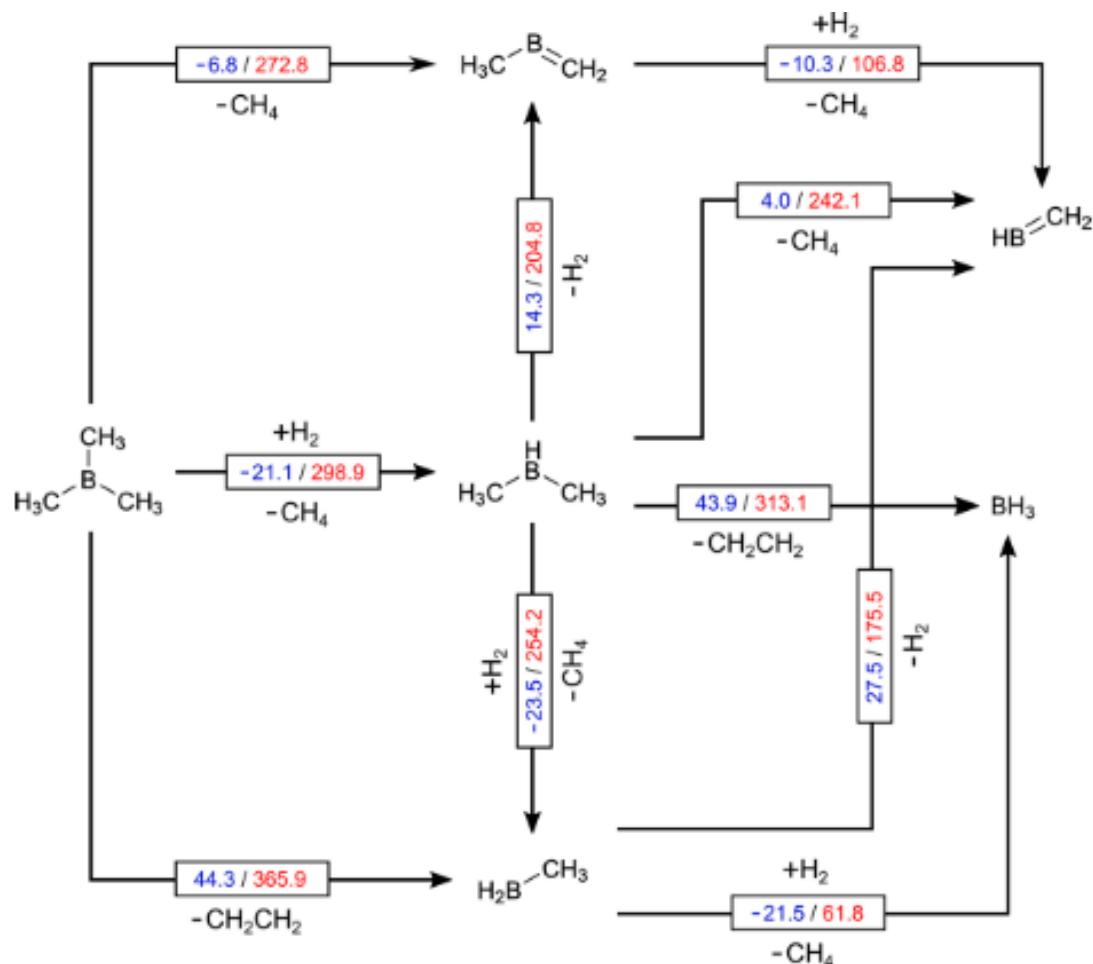
## Boron-Carbon films from Trimethylboron

From Quantum chemical calculations:  
Decomposition in Ar ambient at 800 °C



# Boron-Carbon films from Trimethylboron

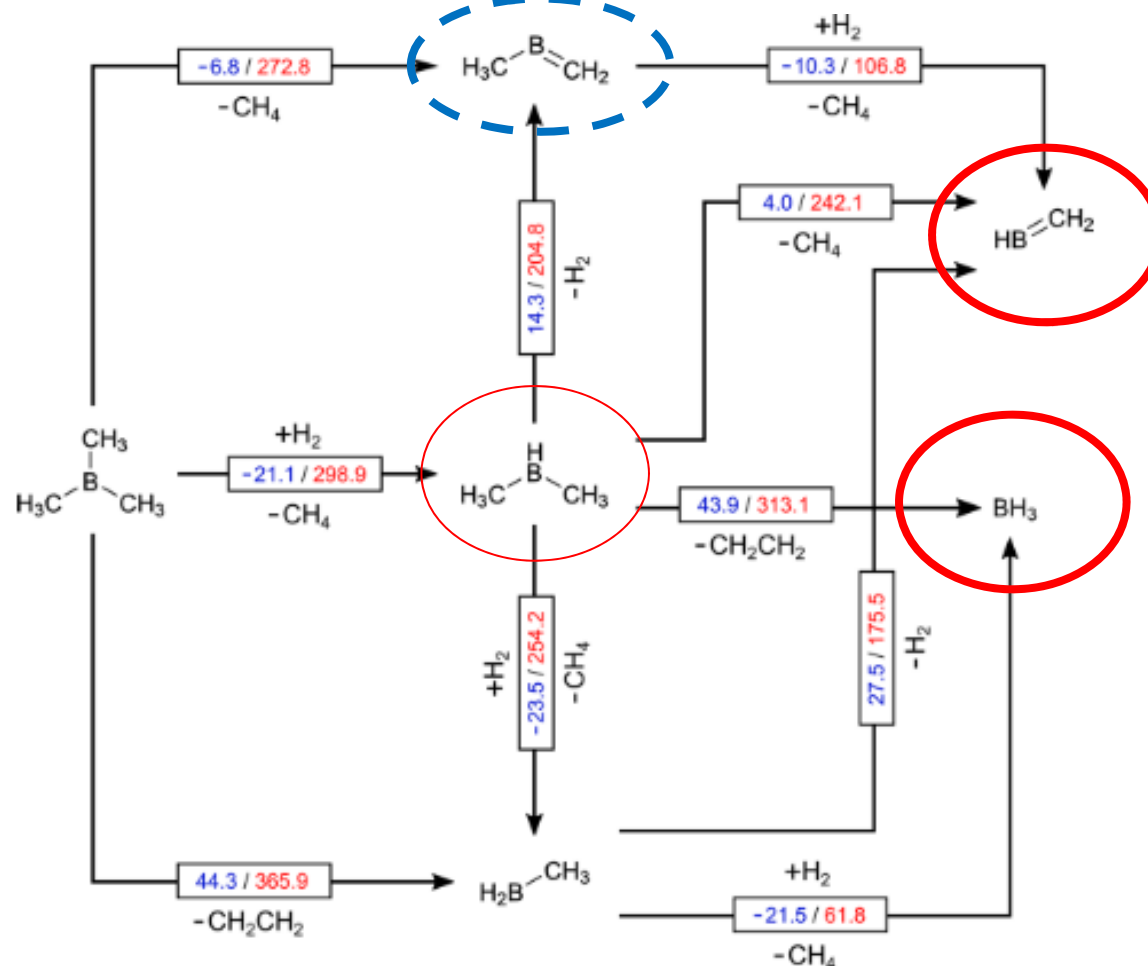
Decomposition  
pathway in  $H_2$



# Boron-Carbon films from Trimethylboron

Decomposition  
pathway in  $H_2$

— in Ar and  $H_2$   
— in  $H_2$



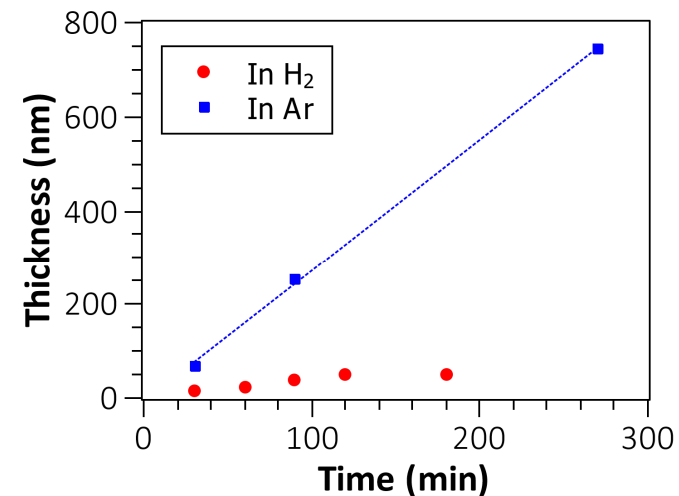
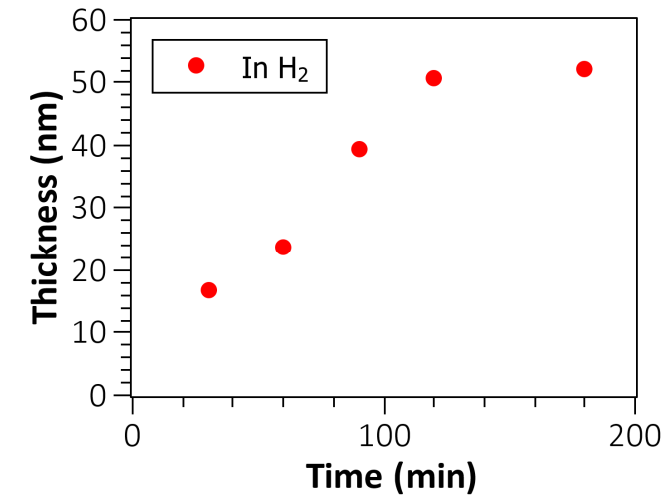
## Motivation for this work

- Observation in hydrogen ambient at 700 °C and 5000 Pa

Deposition time (min)	Thickness (nm)
30	N/A
90	77
270	84

## Experimental conditions

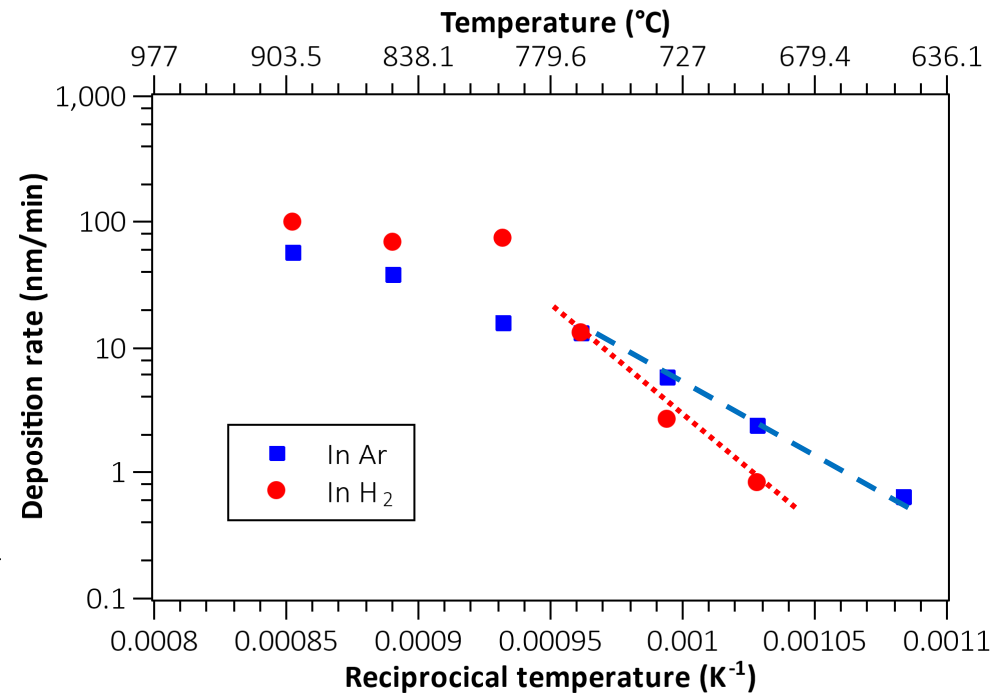
- Observed in H<sub>2</sub>, not in Ar
- Observed at 700 °C, but not at 800 °C
- Saturated thickness:  $\approx 100$  nm at 5000 Pa and 700 °C (usually between 70 and 150 nm)





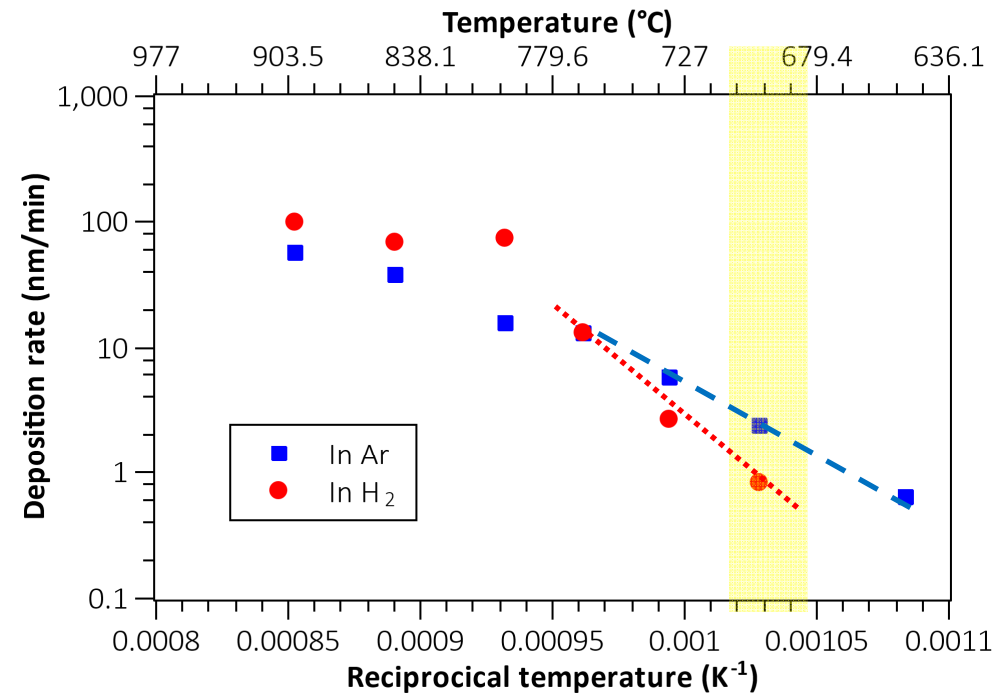
## Arrhenius plots for TMB pyrolysis

- in Ar:
  - $E_A$ : 202.8 kJ/mol
  - $K$ :  $1.96 \times 10^{11}$
- in  $H_2$ :
  - $E_A$ : **341.8 kJ/mol**
  - $K$ :  $1.78 \times 10^{18}$



## Arrhenius plots for TMB pyrolysis

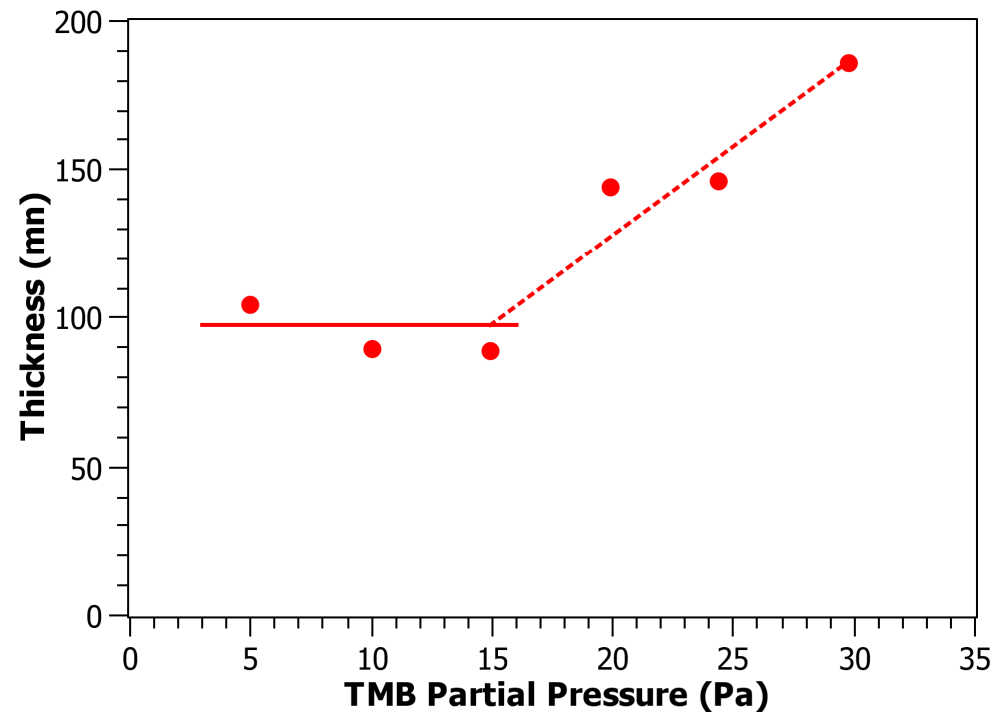
- Deposition regime:
  - Kinetically limited-regime:  
⇒ Growth rate depends only on:
    - precursor partial pressure
    - number of free deposition sites



## Respective effects of TMB and H<sub>2</sub>

- Deposition at constant hydrogen pressure (5000 Pa H<sub>2</sub>, 60 min):  
two regimes

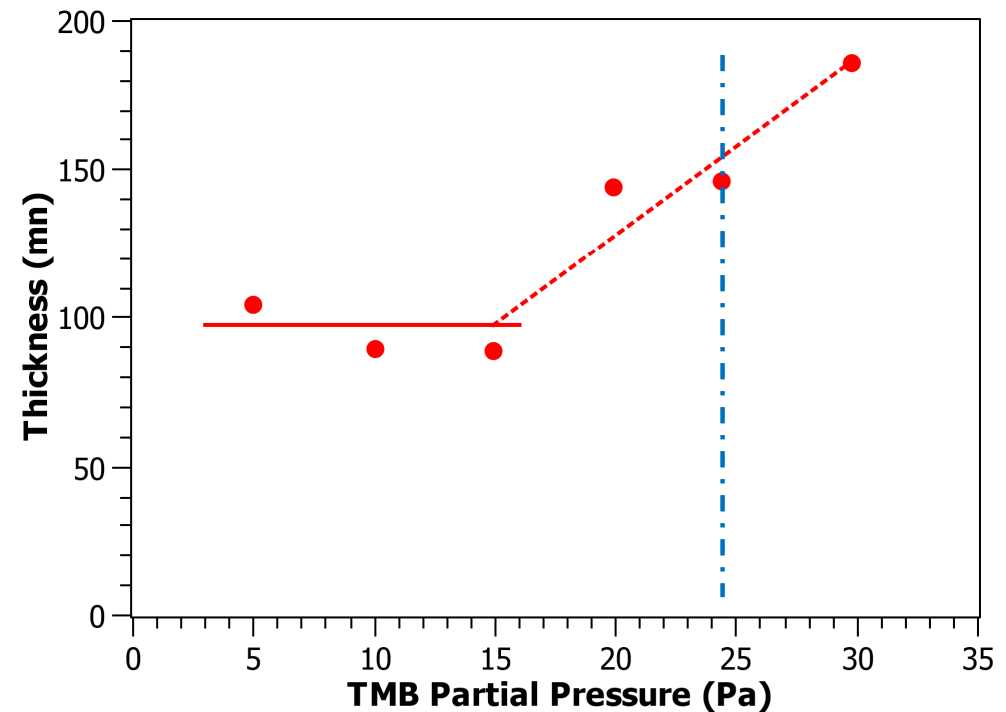
- Saturated growth  
below 15 Pa TMB
- Linear behaviour  
above 15 Pa TMB



## Respective effects of TMB and H<sub>2</sub>

- Deposition at constant hydrogen pressure (5000 Pa H<sub>2</sub>, 60 min) : two regimes

- Saturated growth below 15 Pa TMB
- Linear behaviour above 15 Pa TMB

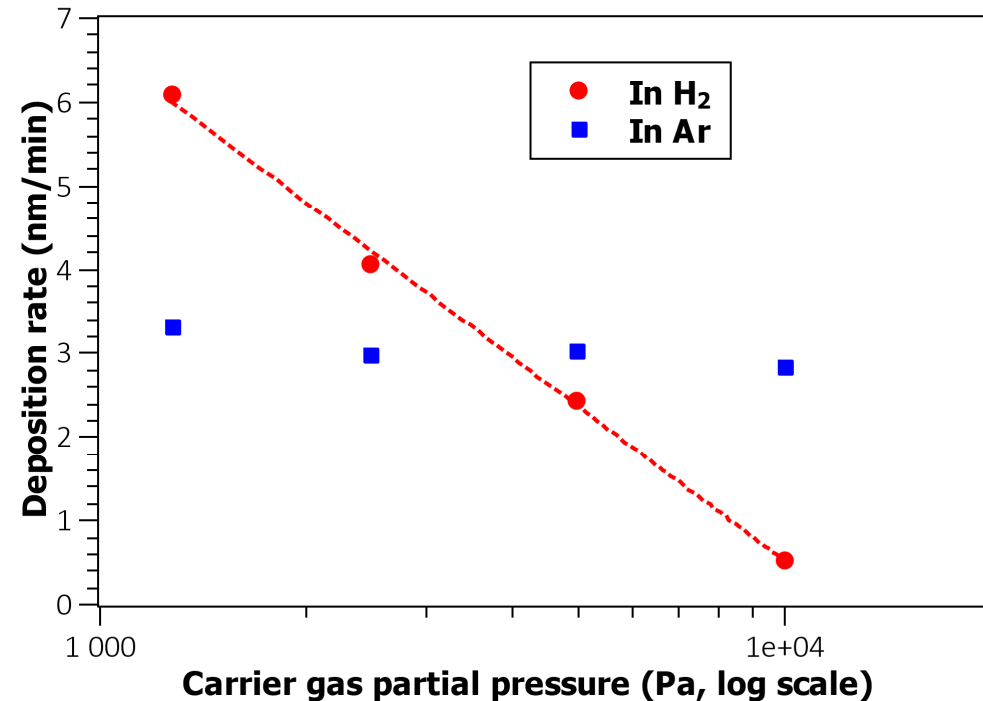


## Respective effects of TMB and H<sub>2</sub>

- Deposition at constant TMB pressure (24.5 Pa, 60 min)

$$P_{H_2} = \frac{F_{H_2}}{(F_{H_2} + F_{TMB})} P \approx P$$

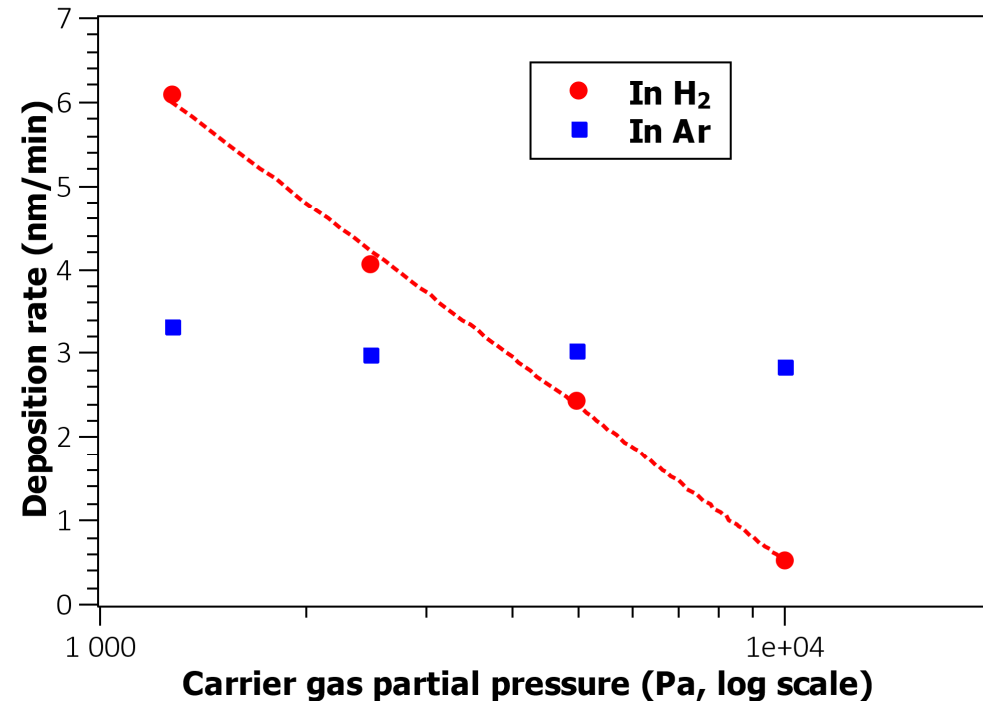
$$P_{TMB} = \frac{F_{TMB}}{(F_{H_2} + F_{TMB})} P$$
$$\approx \frac{F_{TMB}}{F_{H_2}} P$$



## Respective effects of TMB and H<sub>2</sub>

- Deposition at constant TMB pressure (24.5 Pa, 60 min)

- In Ar: constant
- In H<sub>2</sub>: growth rate decreasing prop. to  $\log(P_{H_2})$
- This was also observed for 120 min deposition



# Hypotheses

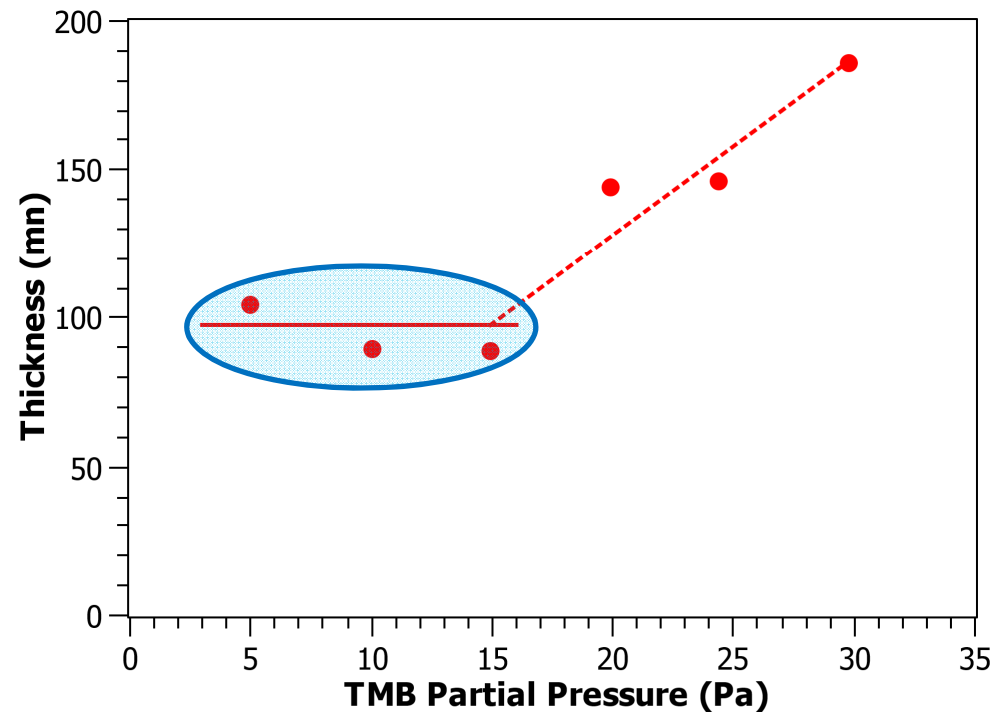
- Non-sticking/reacting products of decomposition in  $H_2$
- Etching
- Surface poisoning
- Competitive adsorption

## Possible explanation

- Non-sticking products?

Can explain growth rate drop

Cannot explain the behaviour observed by changing  $P_{TMB}$





## Possible explanation

- Hydrogen etching?

Process	Film thickness (nm)
60 min growth	146.3
30 min growth + 60 min H <sub>2</sub> exposure + 30 min growth	156.3

The thickness is same within experimental error

=> Etching cannot explain the phenomenon

## Possible explanation

- Surface poisoning?

Process	Film thickness (nm)	Expected (nm)
180 min at 3.25 Pa TMB + 60 min at 27 Pa TMB	500	≈ 100

Growth can be resumed after exposure 3 hours deposition in conditions that afford inhibited growth

=> The surface did not become inactive

## Possible explanation

- Dynamic coverage by hydrogen:
  - Possible considering a Temkin adsorption isotherm
  - Heterogeneous surface

$$GR = (1 - \theta_T) GR_0$$

$$GR = \left(1 - \frac{RT}{b} \ln(A * P_{H_2})\right) GR_0$$

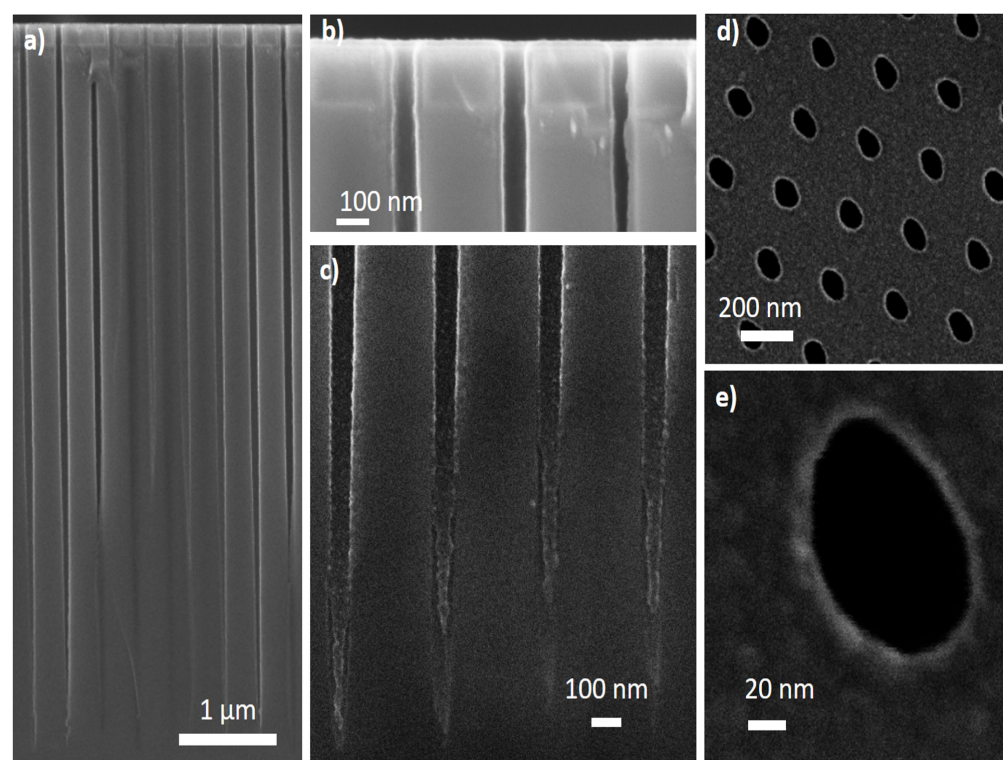
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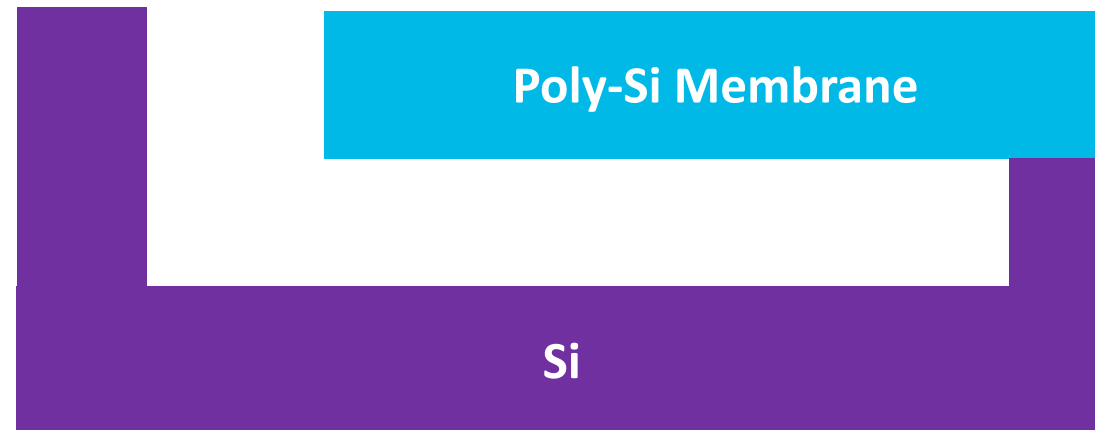
## Application to high aspect ratios

- Deposition in 60:1 aspect ratio vias
- 30 nm thick on top
- Reach bottom without clogging



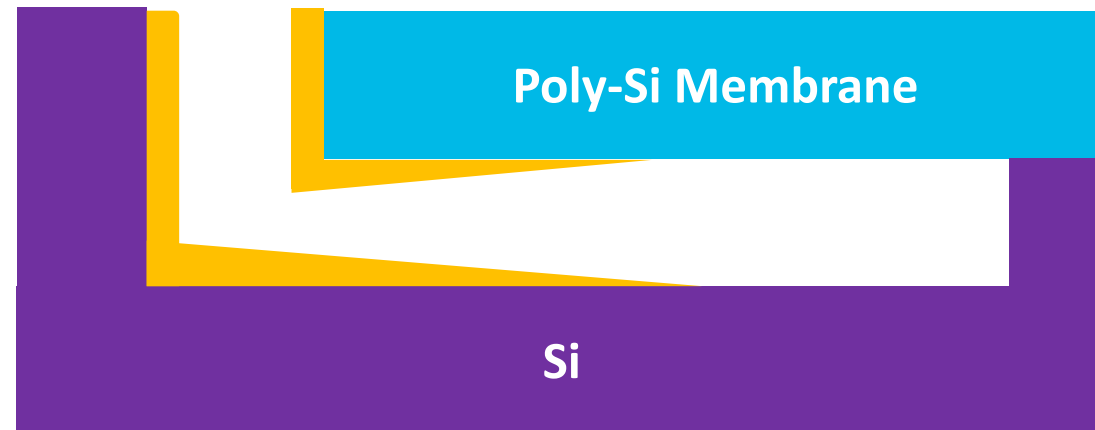
## Application to high aspect ratios

- Deposition in lateral high aspect ratio structures (up to 10048:1, 500 nm gap)



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- Deposition in lateral high aspect ratio structures (up to 10048:1, 500 nm gap)



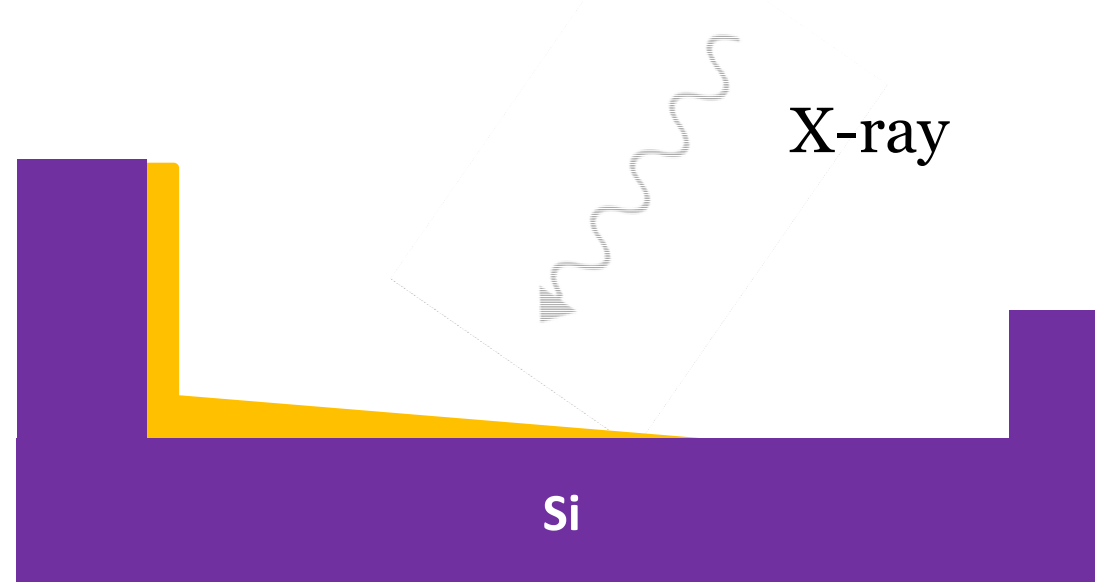
## Application to high aspect ratios

- Deposition in lateral high aspect ratio structures (up to 10048:1, 500 nm gap)



## Application to high aspect ratios

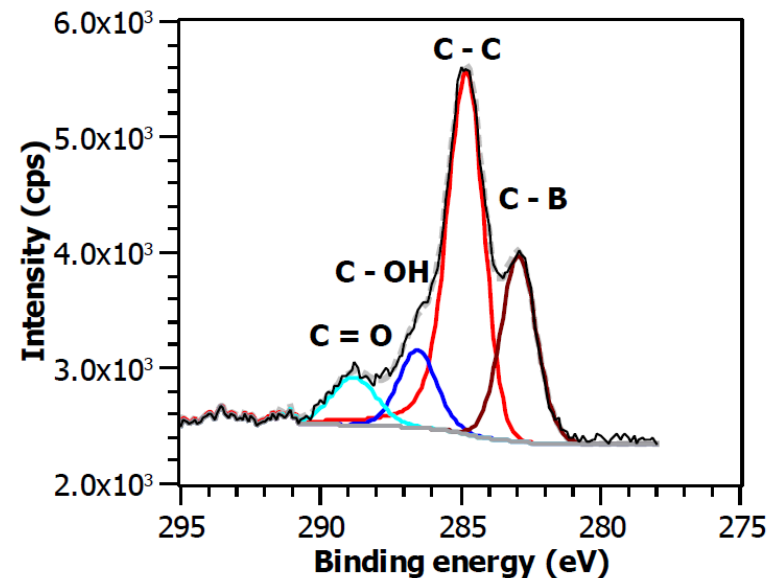
- X-ray photo electron spectroscopy (XPS) in lateral high aspect ratio structures (up to 10048:1, 500 nm gap)





## Application to high aspect ratios

- Deposition in 10048:1 lateral high aspect ratio structures (500 nm gap)
- XPS at AR  $\approx$  2500:1 :
  - B/C = 0.45 in trench, (0.5 outside)



## Conclusion

- We show inhibition of B-C film growth in  $H_2$ , 700 °C and 5000 Pa
- We propose that inhibition is due to competitive adsorption between TMB and  $H_2$  and that  $H_2$  adsorption can be described by a Temkin isotherm
- We can deposit B-C thin films in deep features at these conditions

## Acknowledgments

- Pedersen group and functional materials unit at LiU



- Financial support

Financial support from The Swedish Foundation for Strategic Research (SSF) under contract IS14-0027 is gratefully acknowledged. H.H. and H.P. acknowledge financial support from the Swedish Government Strategic Research Area in Materials Science on Functional Materials at Linköping University (Faculty Grant SFO-Mat-LiU No. 2009-00971).

Thank you for your attention!

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